

## STANDARD WINDOW LEAD TIMES

Our Team Specializes in

Standard Rigid ..... 10 Days

Flex + Rigid-Flex ..... 15 Days

24 hr Turnaround Available

## TOLERANCES

### Design & Test

- Trace Tolerance ..... + / - .0008"
- Internal Drill to Cp ..... .007"
- Pad Over FHS ..... .004"
- Soldermask Clearance Over PAD Size ..... .005"
- From Cp to the Edge of the Board ..... .010"
- Impedance ..... + / - 10%

### Lamination

- Board Thickness ..... + / - .005"
- Layer to Layer Registration ..... .004"

### Drill & Rout

- Route ..... + / - .005"
- Inside Radius ..... .015"
- Minimum Slot Width ..... .021"
- Drill Positioning ..... + / - .002"
- From Cp To The Edge of the Board ..... .010"
- Impedance ..... + / - 10%

## CAPABILITIES

### Design & Test

- 2 mil Trace Width
- 3 mil Air Gap
- IPC Class 2 / IPC Class 3
- Flying Probe Net List Test
- Differential Impedance
- TDR Testing
- Automatic Optical Inspection

### Lamination

- 1 to 30 Layers
- Vacuum Lamination
- Sequential Lamination

### Drill & Rout

- Counter Sinks / Counter Bores
- Scoring / Rout & Retain
- Laser Route
- Blind Vias / Buried Vias
- Stacked Vias

### Materials

- Flex and Rigid-Flex
- Kapton & Non-Kapton
- RF and High Speed Materials
- Mix Materials / FR-4 Teflon
- Metal Back Boards (LED / Power Distribution)
- Heavy Cp 6 oz. Finish Rigid and Rigid-Flex

### Plate

- Conductive Via Fill
- Non-Conductive Via Fill
- Plated Edges
- Plated Radii (Castellation)
- Hard Gold Body / Soft Bondable Gold
- Immersion Gold
- HAL Lead Free (RoHS)
- HAL Standard
- Immersion Silver
- Entek (OSP)

### Certifications

- UL ISO / AS 9100
- MIL-SPEC 31032 / 1B & 31032 / 4A
- ITAR
- IPC
- ODB++

